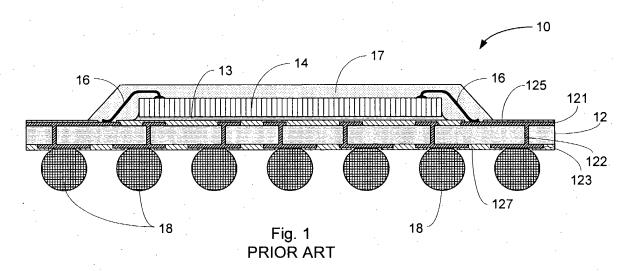
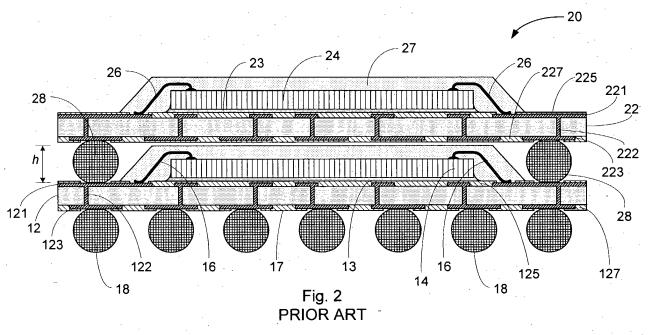
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
Having Wire Bond Interconnect...
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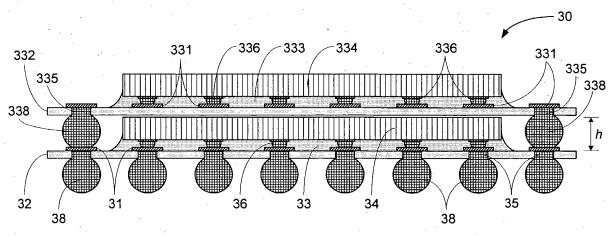


Fig. 3 PRIOR ART

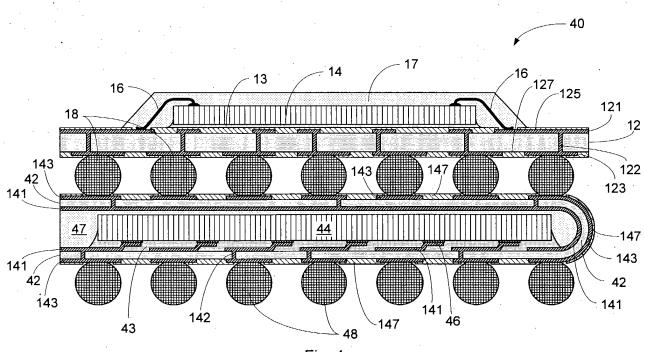
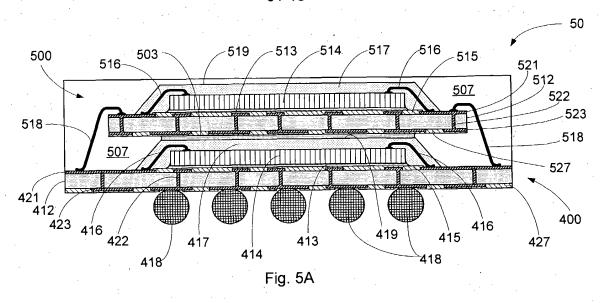
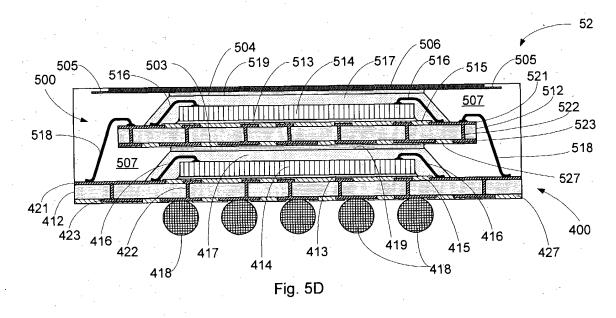
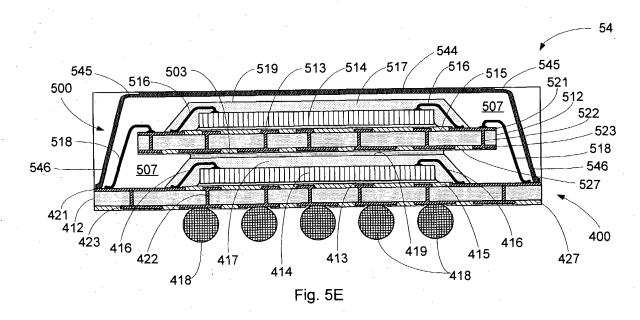


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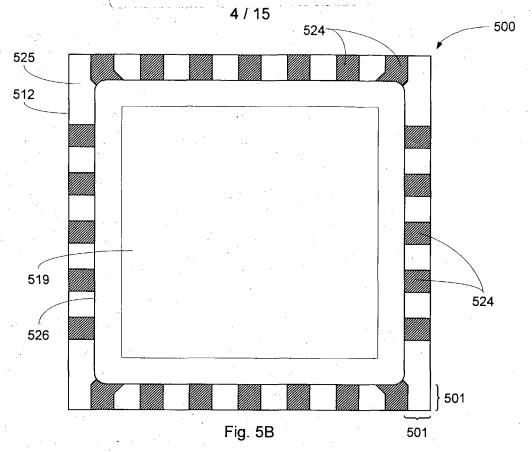
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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Title: Semiconductor Multi-Package Module
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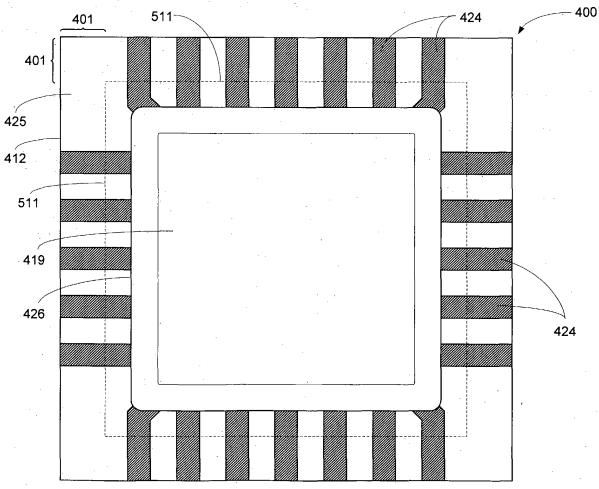
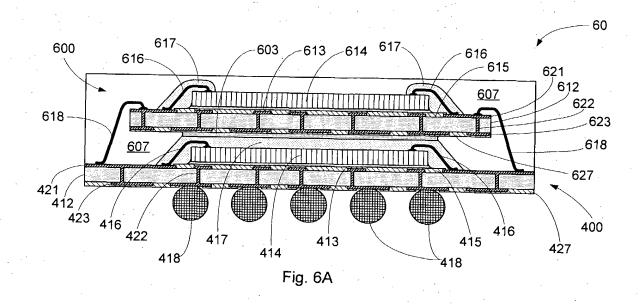
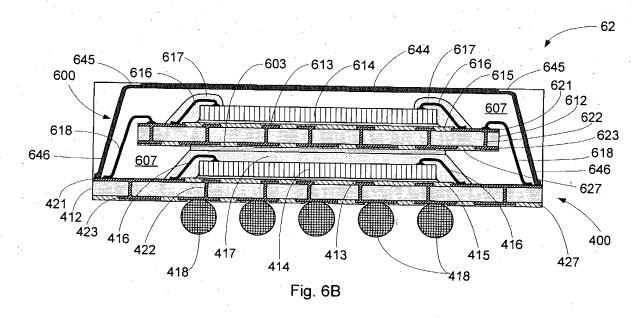
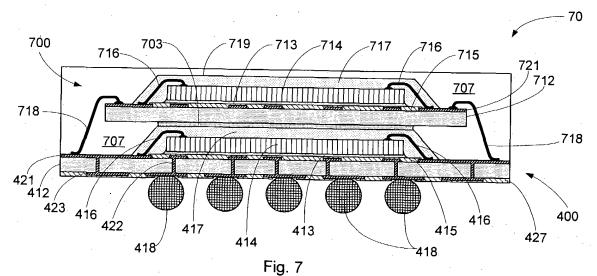


Fig. 5C

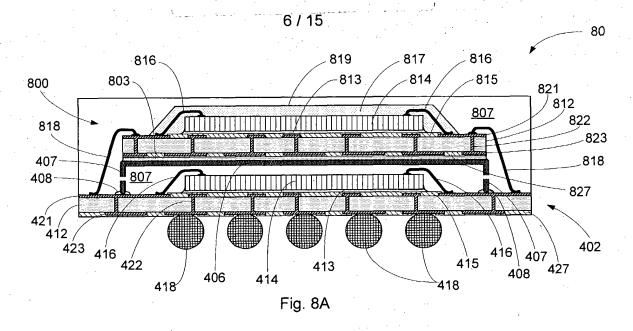
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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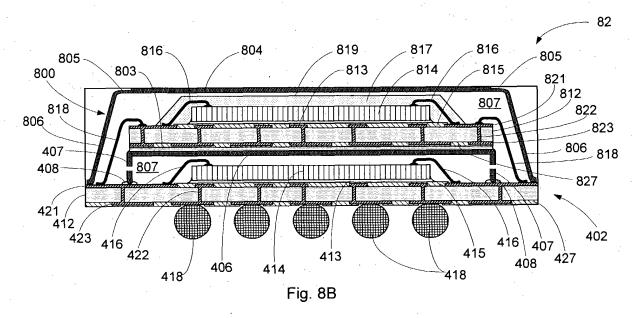


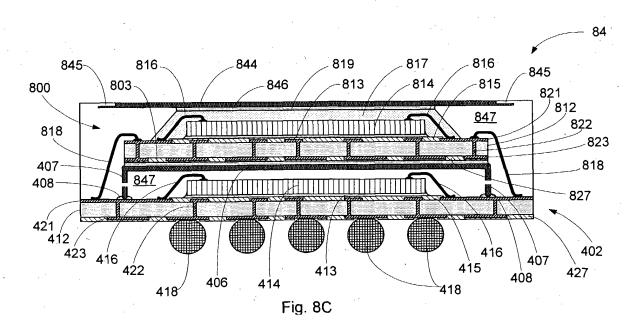




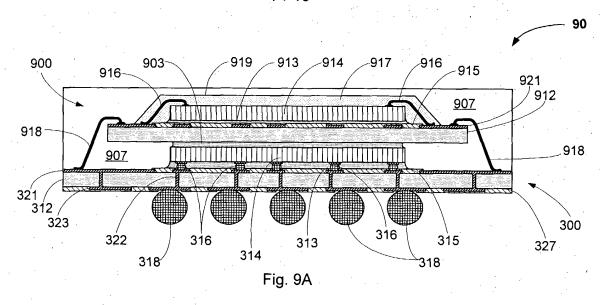
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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Attorney Docket: CPAC 1017-4 D2
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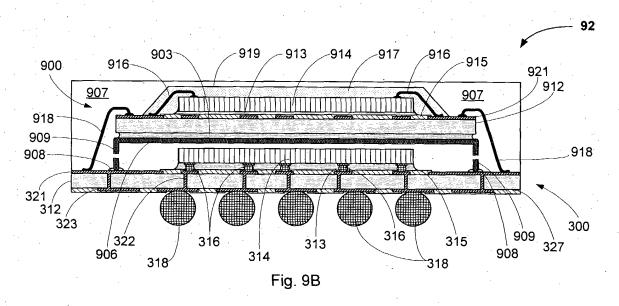


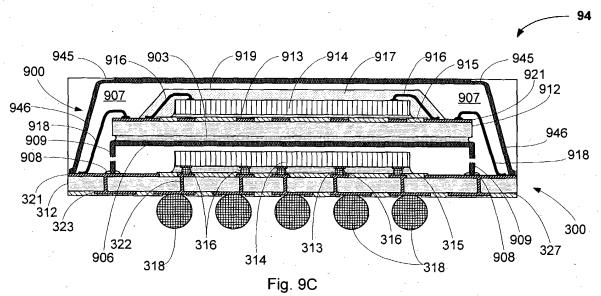




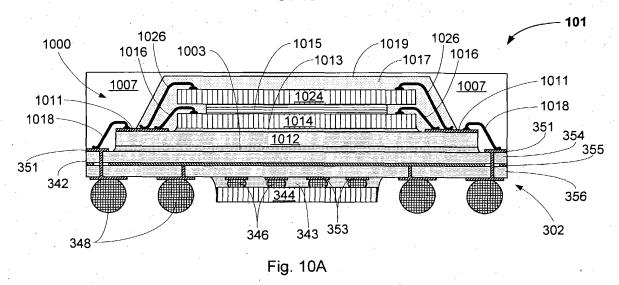
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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Attorney Docket: CPAC 1017-4 D2
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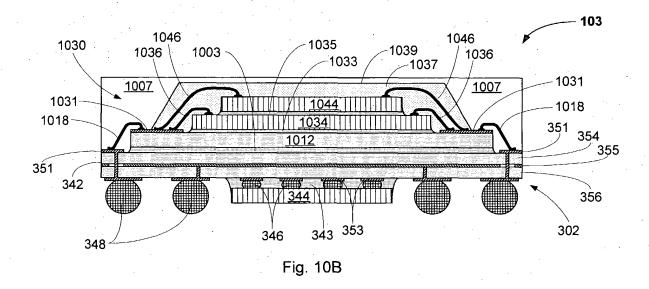


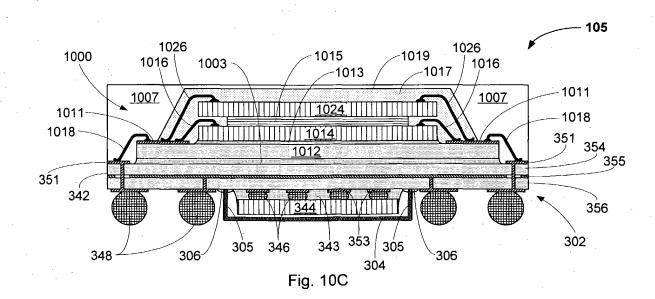




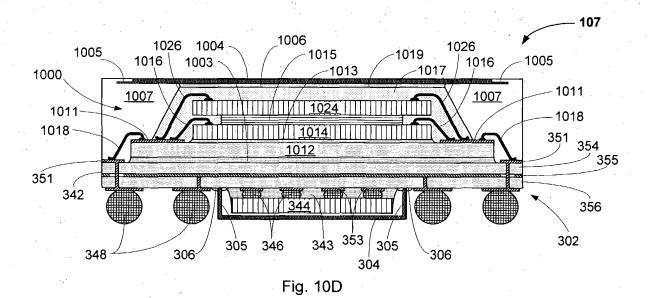
Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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Inventor: Marcos Karnezos
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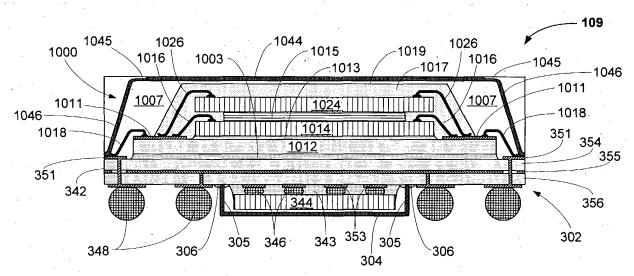


Fig. 10E

Having Wire Bond Interconnect... Attorney Docket: CPAC 1017-4 D2 Sheet 10 of 15 10 / 15 1402-**PROVIDE** AN UNSINGULATED STRIP OF BGA PACKAGES, WITH SHIELDS AFFIXED, WITHOUT MOLDING. AND WITHOUT SOLDER BALLS 1404-DISPENSE ADHESIVE **OVER SHIELDS** ON "GOOD" BGA PACKAGES 1406~ 1408-**PROVIDE** PICK-AND-PLACE SINGULATED LGA PACKAGES, "GOOD" SINGULATED LGA PACKAGES WITH MOLDING ONTO ADHESIVE OVER SHIELDS AND WITHOUT SOLDER BALLS ON "GOOD" BGA PACKAGES 1410 **CURE ADHESIVE** 1412 PLASMA CLEAN 1414-FORM WIRE BOND **Z-INTERCONNECTIONS** 1416-PLASMA CLEAN 1418-FORM MOLDING 1420-**DEFLASH** 1422-ATTACH SOLDER BALLS 1424-

Inventor: Marcos Karnezos

Title: Semiconductor Multi-Package Module

Fig. 11A

SAW SINGULATE COMPLETED MODULES *

Inventor: Marcos Karnezos
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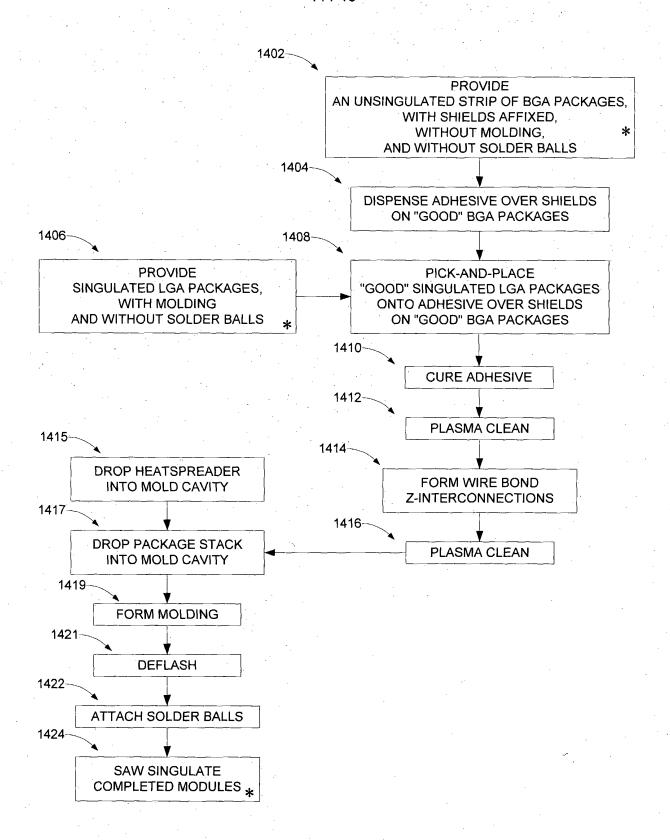


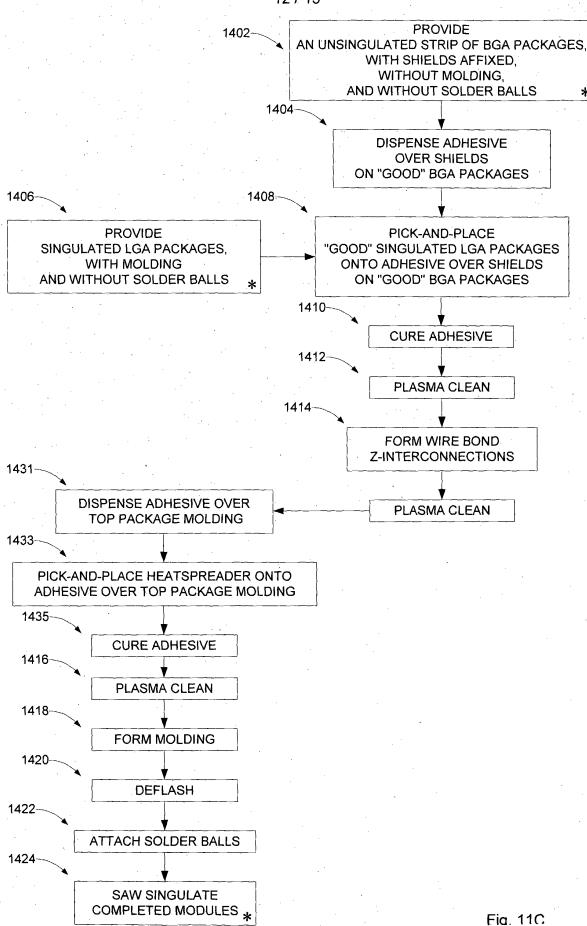
Fig. 11B

Inventor: Marcos Kamezos

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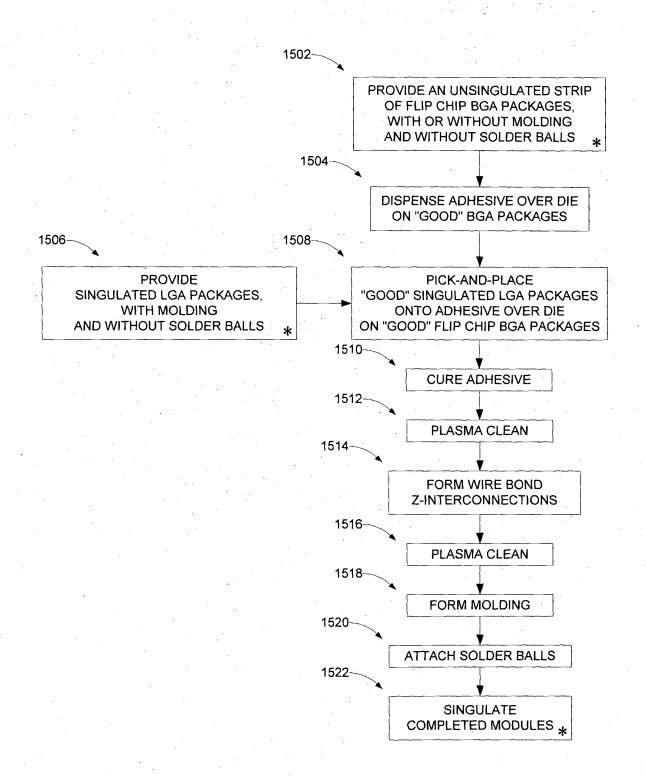


Fig. 12

Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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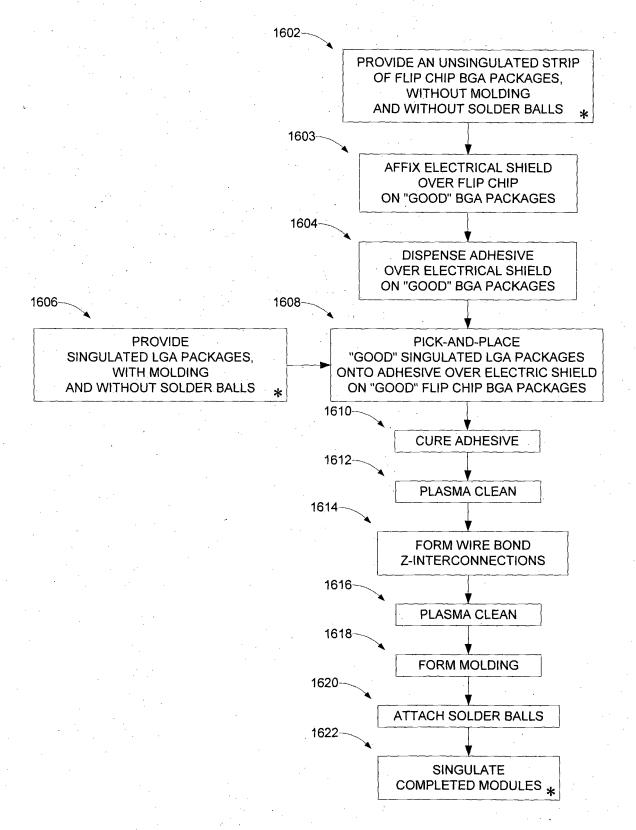


Fig. 13

Inventor: Marcos Karnezos
Title: Semiconductor Multi-Package Module
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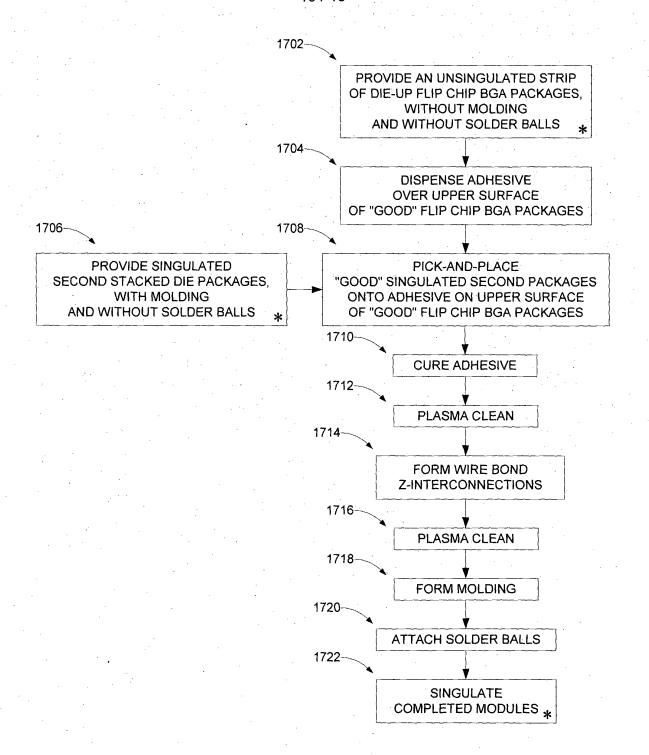


Fig. 14